REMARKS

Favorable reconsideration is respectfully requested.

The claims are 1 to 4.

The above amendment is responsive to points set forth in the Official Action.

Claims 1 to 4 have been rejected under 35 USC 103(a) as being unpatentable over Pine (U.S. 4,361,640).

This rejection is respectfully traversed.

On page 3 in the Official Action, it is pointed out that Pine teaches component (E) in present claim 1 as Pine discloses mixed o,p-toluenesulfonamides (which chemical formula is CH_3 - C_6H_4 - SO_2NH_2) for the plasticizer, and that this compound teaches component (E) having the formula (I), i.e., R^1 -X, in which R^1 is CH_3 - C_6H_4 and X is $-SO_2NHR^2$ wherein R^2 is a hydrogen atom.

However, by the above amendment, the group -SO₂NHR₂ has been deleted from the definition of group X in component (E) in claim 1. Thus, component (E) is <u>not</u> taught or suggested by Pine.

Moreover, Pine fails to teach or suggest that the incorporation of compound (E), where SO_2NHR^2 is deleted from the listed species of group X of the present invention, and that by which the advantageous effect of a deep non-printing depth is obtained and excellent resolving properties are exhibited.

In the Pine reference, mixed o,p-toluenesulfonamides are used as a plasticizer, and no other effect resulting from the compound is disclosed.

Those skilled in the art who read the Pine reference would only expect that incorporation of the plasticizer such as mixed o,p-toluenesulfonamides will produce a good plasticizing effect. The art skilled would not be motivated to think of the effect of increase in the depth of non-printing area from such reference.

In view of the foregoing, the invention of claim 1 as well as the inventions of claims 2 - 4 dependent on claim 1, are not taught or suggested by Pine.

No further issues remaining, allowance of this application is respectfully requested.

If the Examiner has any comments or proposals for expediting prosecution, please contact undersigned at the telephone number below.

Respectfully submitted,

Hiroshi TAKANASHI et al.

Matthew Jacob

Registration No. 25,154 Attorney for Applicants

MJ/pjm Washington, D.C. 20006-1021 Telephone (202) 721-8200 Facsimile (202) 721-8250 February 21, 2002

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Amended) A photosensitive resin plate comprising a support having formed thereon directly or via an adhesive layer a photosensitive layer of from 0.45 to 0.8 mm in thickness comprising a negative working photosensitive resin composition consisting essentially of (A) a film-forming polymer, (B) an unsaturated compound having a radical polymerizable ethylenic double bond, (C) a photopolymerization initiator, (D) a thermal polymerization inhibitor, and (E) at least one member selected from compounds represented by following formula (I):

$$R^1-X$$
 (I)

wherein -X represents -OR², -COOH, -SO₃H, -CONHR², -COR², [-SO₂NHR²,]
-HNCONHR², or -HNCOOR²; R¹ and R², which may be the same or different, each represents a hydrogen atom, a substituted or unsubstituted, saturated or unsaturated hydrocarbon group, provided that it does not contain a radical polymerizable ethylenic double bond, a substituted or unsubstituted alicyclic hydrocarbon group, a substituted or unsubstituted aromatic hydrocarbon group, or a heterocyclic group, wherein said hydrocarbon group, alicyclic hydrocarbon group, aromatic hydrocarbon group, or the heterocyclic group may have an ether bond in the chain, provided that when -X is -OH, the R¹ represents a group other than a hydrogen atom and an aromatic hydrocarbon group, in a range of from 0.001 to 0.3% by weight based on the weight of the photosensitive resin composition components (A) to (E).